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## (54) PHOTOSENSITIVE RESIN COMPOSITION

(57)Abstract:

PROBLEM TO BE SOLVED: To ensure high sensitivity and resolution and to obtain a resin layer excellent in heat resistance by incorporating a cis-diene substituted polyamic acid having a specified structure unit or a polyimide and an oxvgen sensitizer.

SOLUTION: The photosensitive resin composition contains a cis-diene substituted polyamic acid having a structural unit of the formula or a polyimide and an oxygen sensitizer. In the formula, at least one of R1-R4 is a monovalent organic group having a cis-diene structure, the remainders are each H, hydroxy, carboxyl, a 1-20C alkyl or a 1-20C alkoxyl, X1 and X2 are each O, S, a 1-4C alkylene or a 1-4C alkyleneoxy, Ar1 and Ar2 are each a divalent aromatic group, I1, I2, m1 and m2 are each 0 or 1, where when I1 is 1, m1 is also 1, and when I2 is 1, m2 is also 1.

$$N \leftarrow A r \frac{1}{2H_1} \left( X^{\frac{1}{2}} \frac{1}{H_1} + \frac{R^2}{R^2} \frac{1}{H_2} A r^{\frac{1}{2}} \frac{1}{H_2} N \right)$$

## **LEGAL STATUS**

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